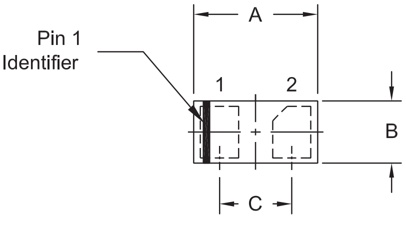
Package Details

TLM2D3D6 Case

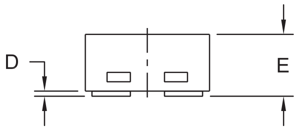

Top View


Bottom View

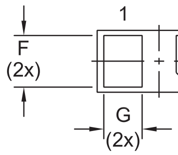
Mechanical Drawing



TOP VIEW



SIDE VIEW



BOTTOM VIEW R2

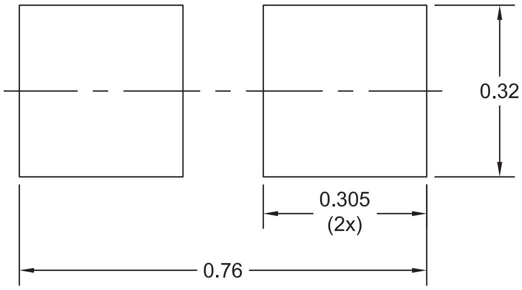
	DIMENSIONS			
	INCHES		MILLIMETERS	
SYMBOL	MIN	MAX	MIN	MAX
A	0.022	0.026	0.55	0.65
B	0.010	0.014	0.25	0.35
C	0.014		0.35	
D	0.000	0.002	0.00	0.05
E	0.011	0.013	0.28	0.32
F	0.008	0.012	0.20	0.30
G	0.005	0.009	0.13	0.24

TLM2D3D6 (REV: R2)

Lead Code:
1) Cathode
2) Anode

Part Marking:
Single Character Alpha/Numeric Code

Mounting Pad Geometry (Dimensions in mm)

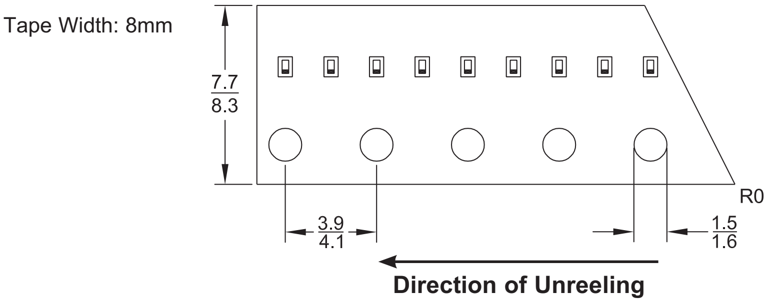


R0

Package Details

TLM2D3D6 Case

Tape Dimensions and Orientation (Dimensions in mm)



Devices are taped in
accordance with
Electronic Industries
Association Standard
EIA-481-1-A

Packaging Base

7” Reel = 8,000 pcs.

Reel Labeling Information

Each reel is labeled with the following information:
Central Part Number, Customer Part Number, Purchase Order Number, Quantity, Lot Number, Date Code, Ship Date and Marking Code.

Reel Packing Information

Reel Size	Reels per Box (Maximum)	Parts per Box (Maximum)	Box Dimensions		Shipping Weight (Max.)	
			INCH	CM	LB	KG
7”	9	72,000	9x9x5	23x23x13	3	2
	18	144,000	9x9x9	23x23x23	6	3
	40	320,000	21x9x9	53x23x23	13	6
	108	864,000	27x9x17	69x23x43	34	16

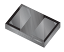
Ordering Information

- For devices taped and reeled on 7” reels, add TR suffix to part number.
- All SMDs are available in small quantities for prototype and manual placement applications.

Material Composition Specification

TLM2D3D6 Case


Top View


Bottom View

Device average mass . . . . 144 µg

Fluctuation margin . . . . +/-10%

Component	Material	Material		Substance	CAS No.	Substance		
		(%wt)	(µg)			(%wt)	(µg)	(ppm)
active device	doped Si	6.92%	10	Si	7440-21-3	6.92%	10	69,247
bond wire	gold	0.28%	0.4	Au	7440-57-5	0.28%	0.4	2,770
leadframe	Cu alloy	27.44%	39.63	Cu	7440-50-8	27.23%	39.33	272,350
				Sn	7440-31-5	0.07%	0.1	692
				Zn	7440-66-6	0.07%	0.1	692
				Cr	7440-47-3	0.07%	0.1	692
die attach	silver epoxy	2.77%	4	Ag	7440-22-4	1.94%	2.8	19,389
				epoxy resin	Proprietary	0.83%	1.2	8,310
encapsulation*	EMC GREEN	62.32%	90	silica (fused)	60676-86-0	52.97%	76.5	529,742
				epoxy resin	29690-82-2	4.67%	6.75	46,742
				phenol resin	9003-35-4	1.56%	2.25	15,581
				carbon black	1333-86-4	0.19%	0.27	1,870
				metal hydroxide	1309-42-8	2.93%	4.23	29,292
plating	Ni/Pd/Au	0.26%	0.38	Ni	7440-02-0	0.25%	0.36	2,493
				Pd	7440-05-3	0.01%	0.01	69
				Au	7440-57-5	0.01%	0.01	69

*EMC GREEN molding compound is Halogen-Free.

Disclaimer
The information provided in this Material Composition data sheet is, to the best of our knowledge, correct. However, there is no guarantee to completeness or accuracy, as some information is derived from data sources outside the company.

R1 (3-June 2011)